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Team Nexperia

High-speed switching diodes Rev. 8 — 1 February 2011

Product data sheet

Product profile 1.

1.1 General description

Single high-speed switching diodes, fabricated in planar technology, and encapsulated in small hermetically sealed glass SOD80C Surface-Mounted Device (SMD) packages.

Table 1. **Product overview**

Type number	Package	Configuration
PMLL4148L	SOD80C	single
PMLL4448		

1.2 Features and benefits

- High switching speed: t_{rr} ≤ 4 ns
- Reverse voltage: V_R ≤ 75 V
- Repetitive peak reverse voltage: V_{RRM} ≤ 100 V
- Repetitive peak forward current: I_{FRM} ≤ 450 mA
- Small hermetically sealed glass SMD package

1.3 Applications

- High-speed switching
- Reverse polarity protection

1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
l _F	forward current		[1] -	-	200	mA
I _{FRM}	repetitive peak forward current		-	-	450	mA
V _R	reverse voltage		-	-	75	V
V _F	forward voltage					
	PMLL4148L	I _F = 50 mA	-	-	1	V
	PMLL4448	I _F = 5 mA	620	-	720	mV
		I _F = 100 mA	-	-	1	V
t _{rr}	reverse recovery time		[2] _	-	4	ns

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] When switched from $I_F = 10$ mA to $I_R = 60$ mA; $R_L = 100 \Omega$; measured at $I_R = 1$ mA.



High-speed switching diodes

2. Pinning information

Pinning		
Description	Simplified outline	Graphic symbol
cathode	[1]	
anode	k a	K
		sym006
	Description cathode	Description Simplified outline cathode [1]

[1] The marking band indicates the cathode.

3. Ordering information

Table 4. Ordering information					
Type number	Package				
	Name	Description	Version		
PMLL4148L	-	hermetically sealed glass surface-mounted package;	SOD80C		
PMLL4448		2 connectors			

4. Marking

Table 5. Marking codes	
Type number	Marking code
PMLL4148L	marking band
PMLL4448	marking band

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{RRM}	repetitive peak reverse voltage		-	100	V
V _R	reverse voltage		-	75	V
I _F	forward current		<u>[1]</u> _	200	mA
I _{FRM}	repetitive peak forward current		-	450	mA
I _{FSM}	non-repetitive peak forward	square wave	[2]		
	current	$t_p = 1 \ \mu s$	-	4	А
		t _p = 1 ms	-	1	А
		t _p = 1 s	-	0.5	А

High-speed switching diodes

Table 6. Limiting values ... continued

In accordance with the Absolute Maximum Rating System (IEC 60134).

			,		
Symbol	Parameter	Conditions	Min	Max	Unit
P _{tot}	total power dissipation	$T_{amb} = 25 \ ^{\circ}C$	<u>[1]</u> -	500	mW
Tj	junction temperature		-	200	°C
T _{amb}	ambient temperature		-65	+200	°C
T _{stg}	storage temperature		-65	+200	°C

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] $T_j = 25 \circ C$ prior to surge.

6. Thermal characteristics

Table 7.	Thermal characteristics					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-a)}	thermal resistance from junction to ambient	in free air	<u>[1]</u> -	-	350	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	-	300	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

7. Characteristics

Table 8.Characteristics

 $T_{amb} = 25$ °C unless otherwise specified.

r amb - 20						
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
VF	forward voltage					
	PMLL4148L	I _F = 50 mA	-	-	1	V
	PMLL4448	I _F = 5 mA	620	-	720	mV
		I _F = 100 mA	-	-	1	V
I _R	reverse current	V _R = 20 V	-	-	25	nA
		$V_R = 20 \text{ V}; \text{ T}_j = 150 ^{\circ}\text{C}$	-	-	50	μA
I _R	reverse current					
	PMLL4448	$V_{R} = 20 \text{ V}; \text{ T}_{j} = 100 ^{\circ}\text{C}$	-	-	3	μA
C _d	diode capacitance	V _R = 0 V; f = 1 MHz	-	-	4	pF
t _{rr}	reverse recovery time		<u>[1]</u> -	-	4	ns
V _{FR}	forward recovery voltage		[2] _	-	2.5	V

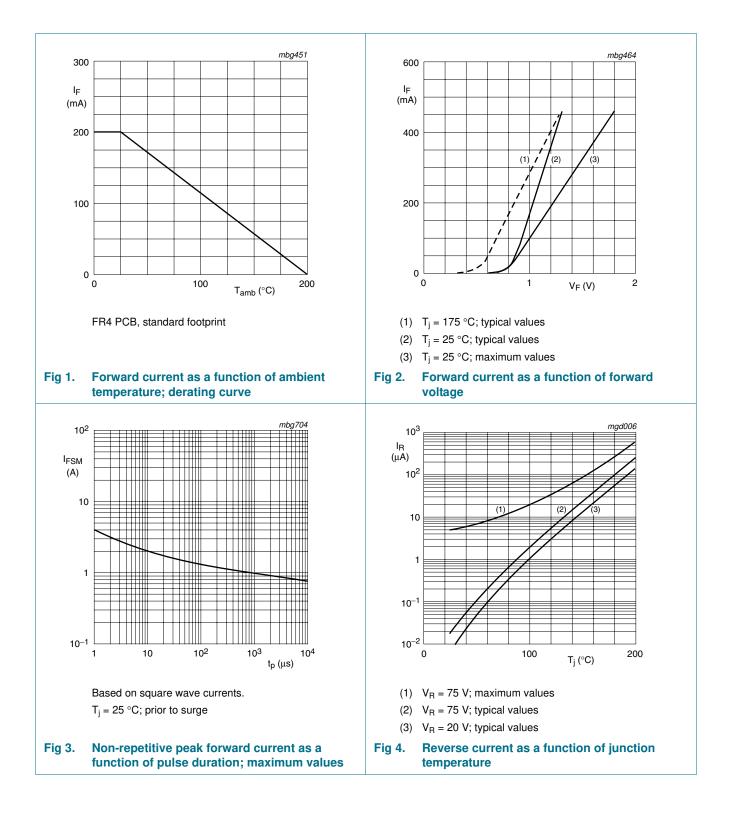
[1] When switched from I_F = 10 mA to I_R = 60 mA; R_L = 100 Ω ; measured at I_R = 1 mA.

[2] When switched from I_F = 50 mA; t_r = 20 ns.

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PMLL4148L; PMLL4448

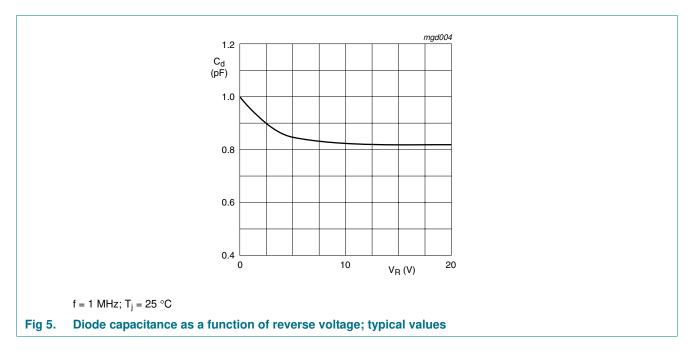
High-speed switching diodes



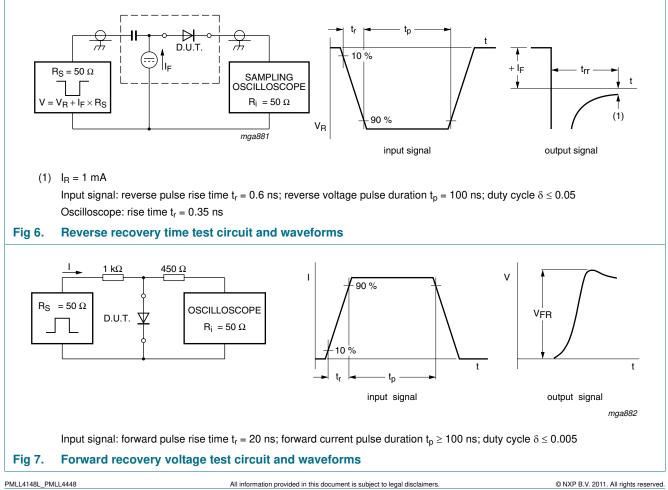
NXP Semiconductors

PMLL4148L; PMLL4448

High-speed switching diodes

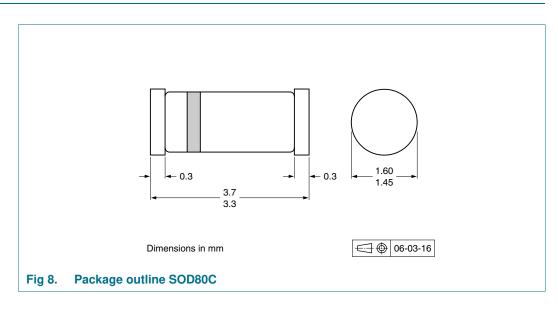


Test information 8.



High-speed switching diodes

9. Package outline



10. Packing information

Table 9. Packing methods

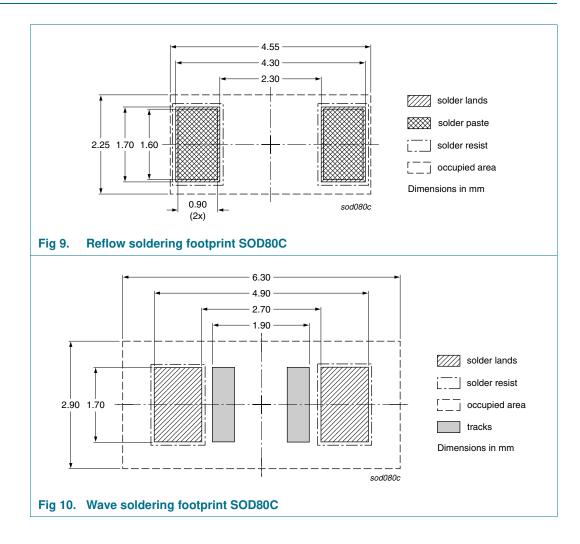
The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number	Package	5 1 51		uantity
			2500	10000
PMLL4148L	SOD80C	4 mm pitch, 8 mm tape and reel	-115	-135
PMLL4448				

[1] For further information and the availability of packing methods, see <u>Section 14</u>.

High-speed switching diodes

11. Soldering



PMLL4148L_PMLL4448

High-speed switching diodes

12. Revision history

Table 10.Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMLL4148L_PMLL4448 v.8	20110201	Product data sheet	-	PMLL4148L_PMLL4448 v.7
Modifications:	Section 4 "M	arking": amended.		
	• Figure 8: rep	laced by minimized outline of	drawing.	
	 Section 13 "L 	<u>egal information"</u> : updated.		
PMLL4148L_PMLL4448 v.7	20070131	Product data sheet	-	PMLL4148L_PMLL4448 v.6
PMLL4148L_PMLL4448 v.6	20050404	Product data sheet	-	PMLL4148L_4448 v.5
PMLL4148L_4448 v.5	20020123	Product specification	-	PMLL4148L_4448 v.4
PMLL4148L_4448 v.4	20001115	Product specification	-	PMLL4148 v.3
PMLL4148 v.3	19990527	Product specification	-	PMLL4148 v.2
PMLL4148 v.2	19960918	Product specification	-	PMLL4148 v.1
PMLL4148 v.1	19960423	Product specification	-	-

13. Legal information

13.1 Data sheet status

Document status[1][2]	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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High-speed switching diodes

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High-speed switching diodes

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